

Electronics Systems (938II)

Lecture 3.3

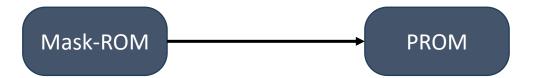
Semiconductor Memories – EPROM and EEPROM



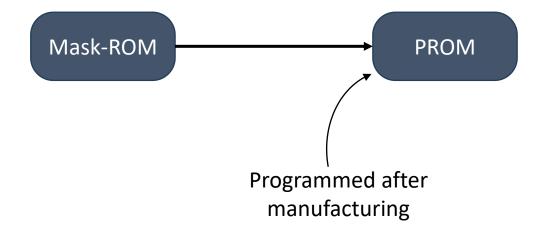
Evolution of Read-Only Memories (ROMs)

Mask-ROM

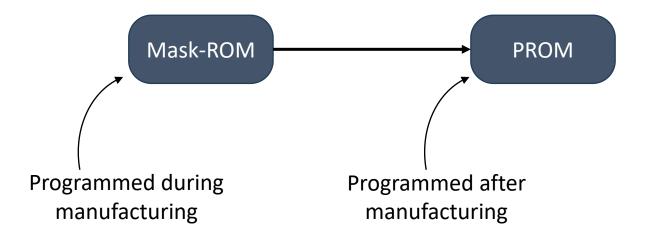






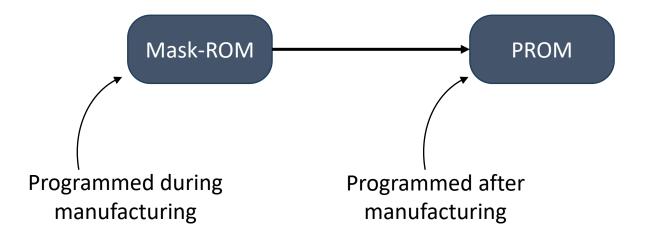






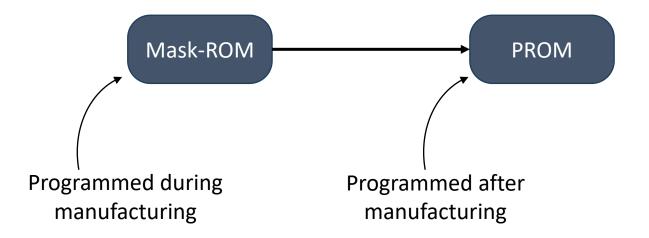


What after?





- Evolution of Read-Only Memories (ROMs)
 - After PROM: Erasable PROM (EPROM)





• Evolution of Read-Only Memories (ROMs)

• After PROM: Erasable PROM (EPROM)

Programmed during Programmed after manufacturing

Programmed during Programmed after manufacturing



• Evolution of Read-Only Memories (ROMs)

• After PROM: EPROM

PROM

PROM

PROM

EPROM

EPROM

EPROM

EPROM

EPROM

EPROM

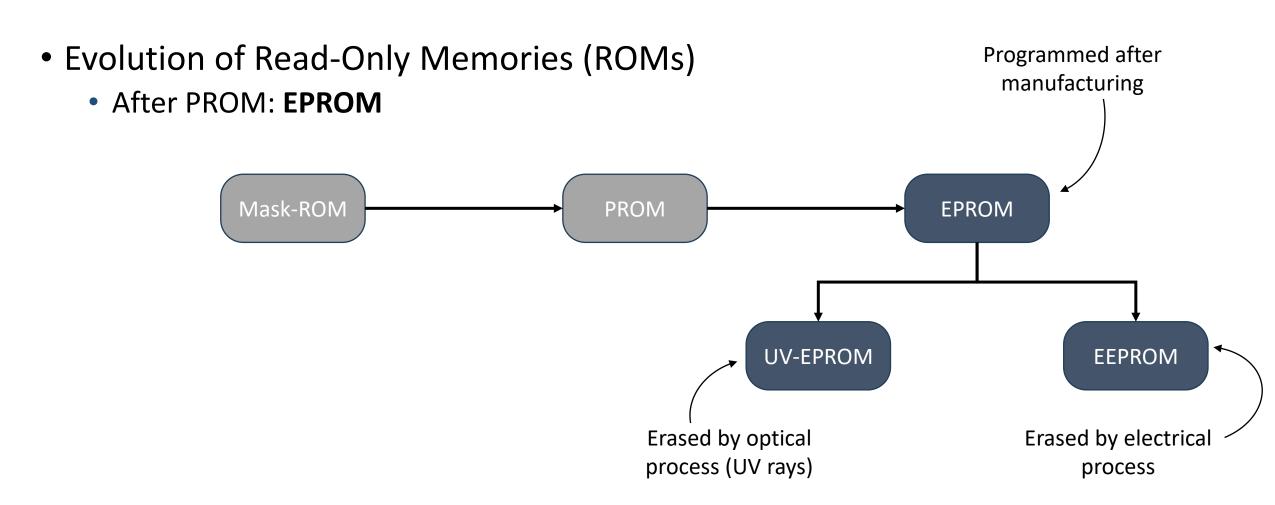
EPROM

EEPROM



 Evolution of Read-Only Memories (ROMs) Programmed after manufacturing After PROM: EPROM Mask-ROM PROM **EPROM UV-EPROM EEPROM** Erased by optical process (UV rays)







- Generally speaking
 - It is a ROM
 - Run-time working principle similar to the that of mask-ROM/PROM
 - That can be programmed
 - And erased
 - So reprogrammed !!!



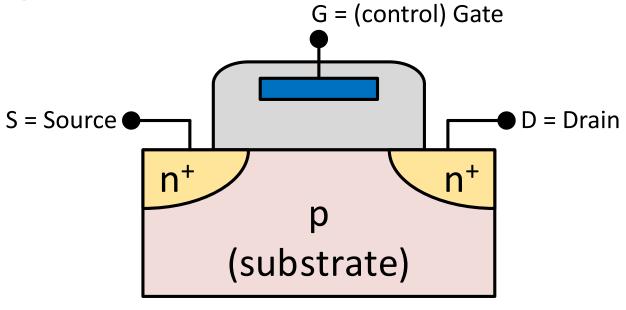
• It relies on particular MOS transistors



- It relies on particular MOS transistors
 - FGMOS = Floating Gate MOS
 - In practice, a MOS + one additional (floating) gate

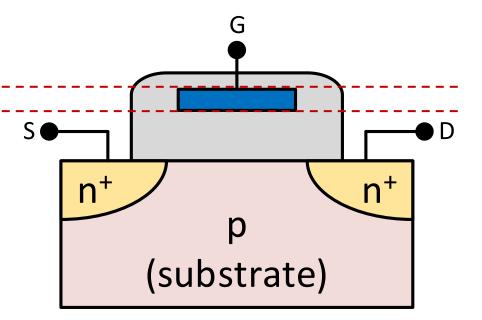


- It relies on particular MOS transistors
 - FGMOS
 - In practice, a MOS + one additional (floating) gate
 - Traditional MOS transistor



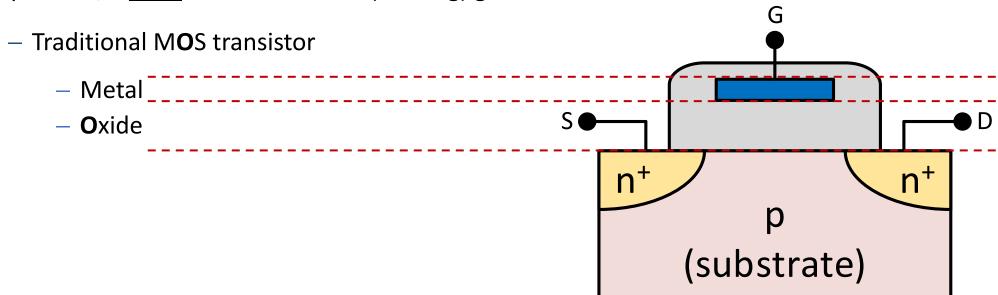


- It relies on particular MOS transistors
 - FGMOS
 - In practice, a MOS + one additional (floating) gate
 - Traditional MOS transistor
 - Metal



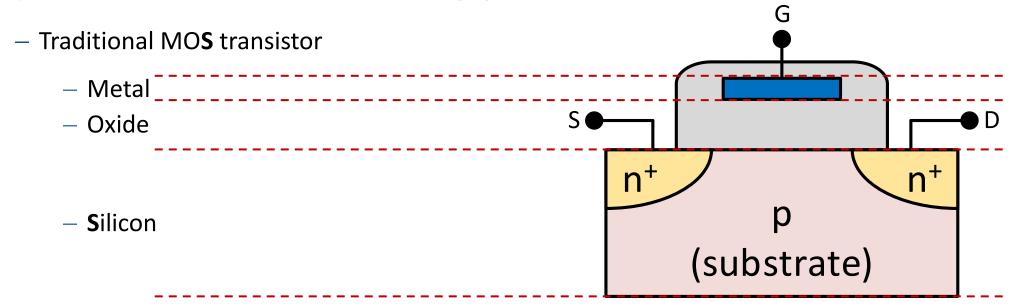


- It relies on particular MOS transistors
 - FGMOS
 - In practice, a MOS + one additional (floating) gate





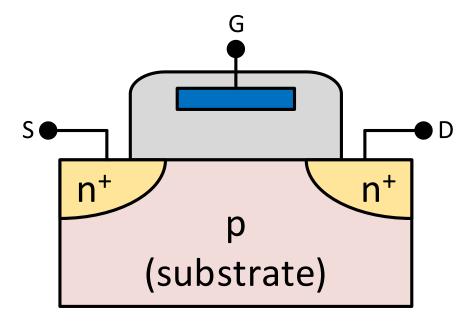
- It relies on particular MOS transistors
 - FGMOS
 - In practice, a MOS + one additional (floating) gate





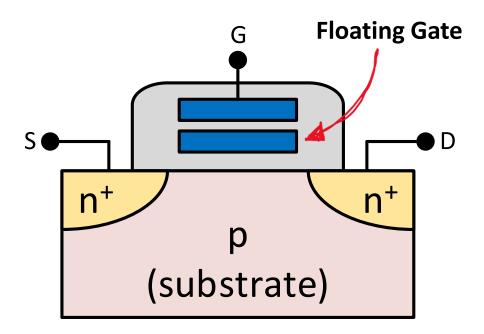
- It relies on particular MOS transistors
 - FGMOS
 - In practice, a MOS + one additional (floating) gate
 - Traditional MOS transistor
 - Metal
 - Oxide

Silicon



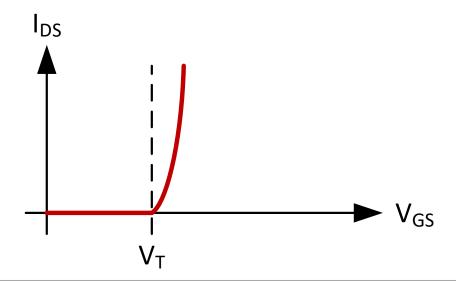


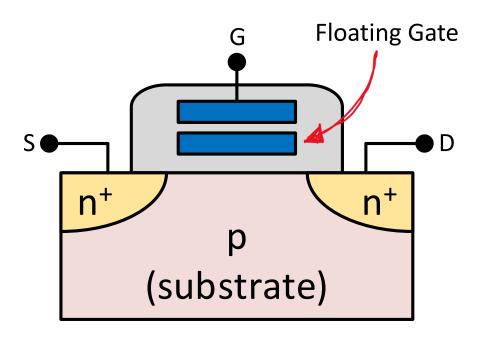
- It relies on particular MOS transistors
 - FGMOS
 - In practice, a MOS + one additional (floating) gate





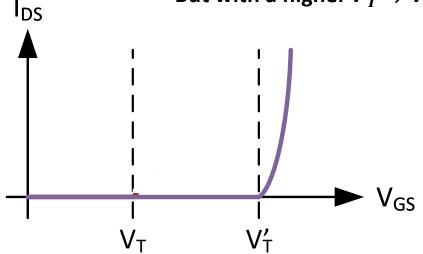
- It relies on particular MOS transistors
 - FGMOS
 - In practice, a MOS + one additional (floating) gate
 - Floating gate = empty (default)
 - It behaves like a "traditional" MOS

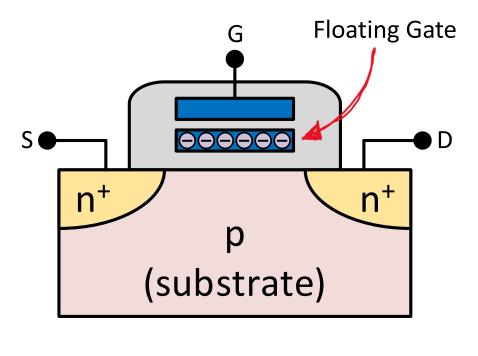






- It relies on particular MOS transistors
 - FGMOS
 - In practice, a MOS + one additional (floating) gate
 - Floating gate = full of electrons (programmed)
 - It behaves like a "traditional" MOS
 - But with a higher $V_T o V_T'$

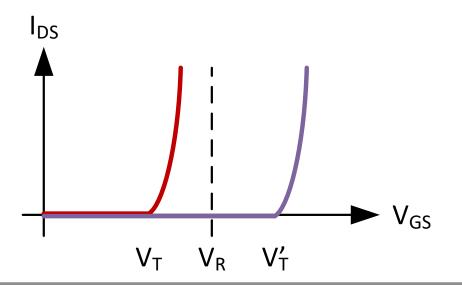


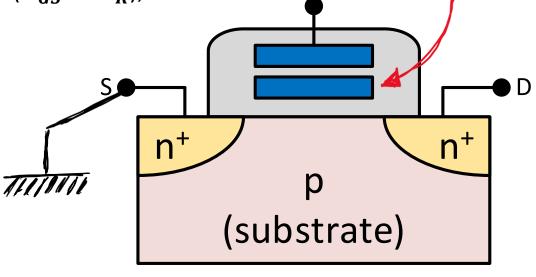




Floating Gate

- It relies on particular MOS transistors
 - FGMOS
 - In practice, a MOS + <u>one additional (floating) gate</u>
 - Using a reading voltage (V_R) on the gate ($V_{GS} = V_R$), such that $V_T < V_R < V_T^\prime$

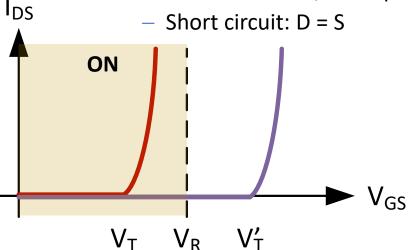


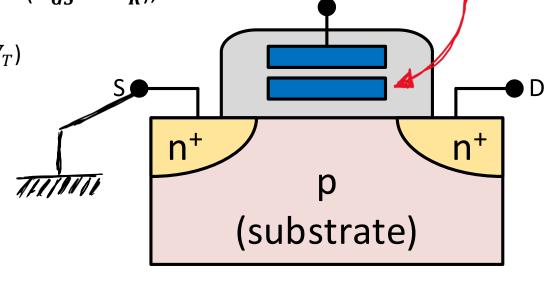




Floating Gate

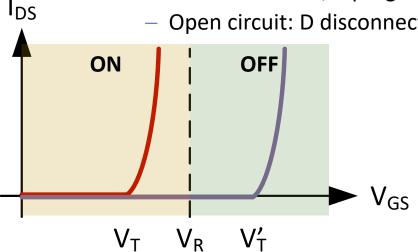
- It relies on particular MOS transistors
 - FGMOS
 - In practice, a MOS + one additional (floating) gate
 - Using a reading voltage (V_R) on the gate $(V_{GS} = V_R)$, such that $V_T < V_R < V_T'$
 - Transistor = ON, if not programmed (V_T)
 - Short circuit: D = S

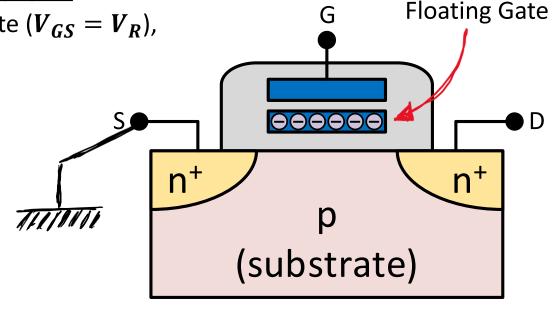






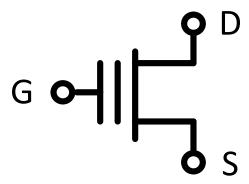
- It relies on particular MOS transistors
 - FGMOS
 - In practice, a MOS + one additional (floating) gate
 - Using a reading voltage (V_R) on the gate $(V_{GS} = V_R)$, such that $V_T < V_R < V_T'$
 - Transistor = OFF, if programmed (V'_T)
 - Open circuit: D disconnected from S





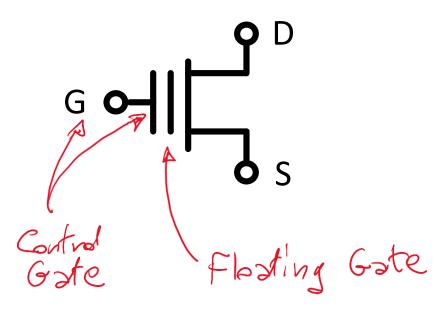


- Applying FGMOS to semiconductor memories architecture ...
 - FGMOS symbol



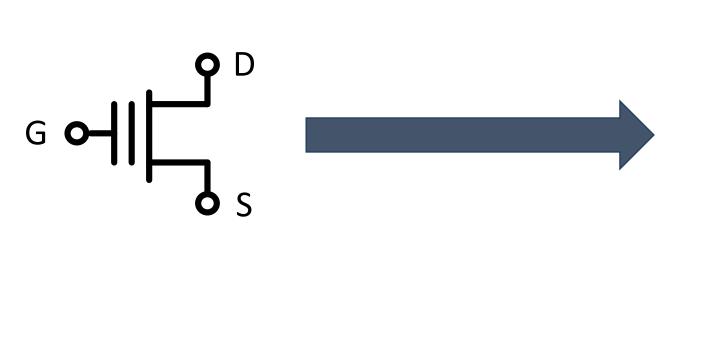


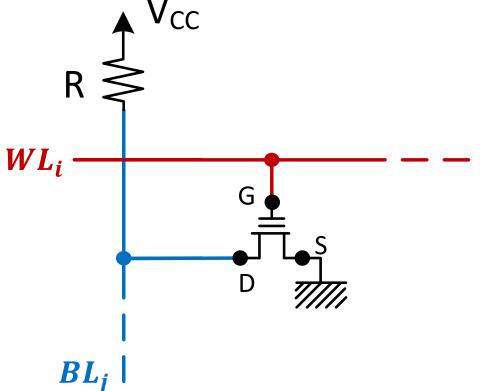
- Applying FGMOS to semiconductor memories architecture ...
 - FGMOS symbol





Applying FGMOS to semiconductor memories architecture ...

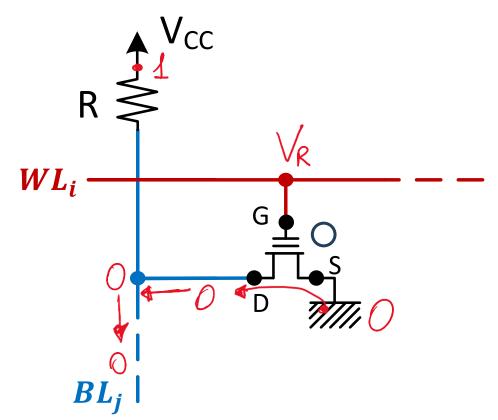




FGMOS symbol



- Applying FGMOS to semiconductor memories architecture ...
 - Working principle
 - FGMOS not programmed
 - Reading with $V_R > V_T$ on WL_i
 - FGMOS = ON
 - − FGMOS = short circuit \rightarrow $D = S \rightarrow V_D = V_S$
 - $-BL_j = 0$ (logic) $= V_D$

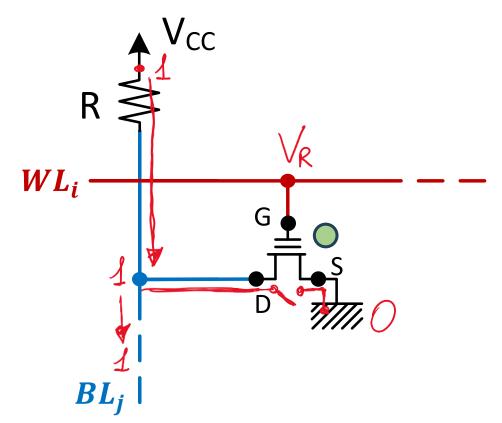




- Applying FGMOS to semiconductor memories architecture ...
 - Working principle
 - FGMOS programmed

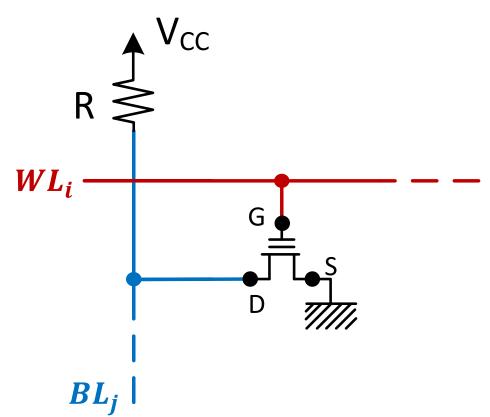


- Reading with $V_R < V_T'$ on WL_i
 - FGMOS = OFF
 - − FGMOS = open circuit $\rightarrow D \neq S \rightarrow V_D \neq V_S$
 - $-BL_{j}=1$ (logic) from pull-up resistor (R)



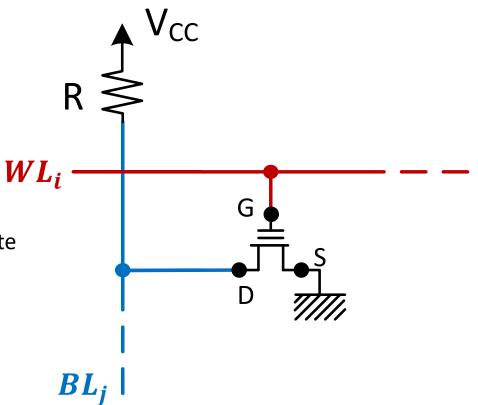


- Applying FGMOS to semiconductor memories architecture ...
 - Why does this work?
 - Because of ...
 - 1. Time required for programming/erasing
 - 2. Data retention
 - 3. Endurance





- Applying FGMOS to semiconductor memories architecture ...
 - Why does this work?
 - Because of ...
 - 1. Time required for programming/erasing
 - Programming = injection of electrons into the floating gate
 - Erasing = removal of electrons from the floating gate
 - Erasing + programming (cycle) takes a time in the order of minutes

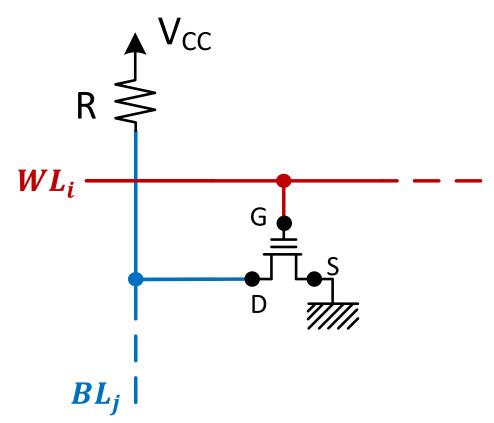




- Applying FGMOS to semiconductor memories architecture ...
 - Why does this work?
 - Because of ...

2. Data retention

- Permanence time of electrons in the floating gate (once injected) $\approx 10 \div 20$ years
- Greater than duration of typical electronic application

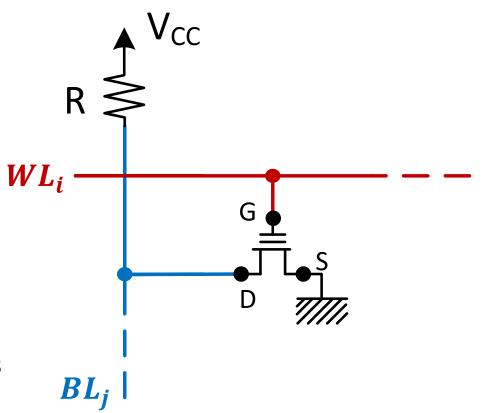




- Applying FGMOS to semiconductor memories architecture ...
 - Why does this work?
 - Because of ...

3. Endurance

- Number of cycles (erasing + programming) = endurance
- Endurance is limited
 - Moving electrons through the oxide degrades it
- However, it is not low: typically, in the range $10^3 \div 10^5$



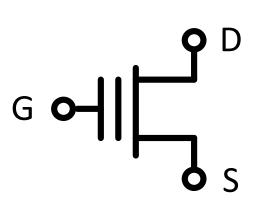


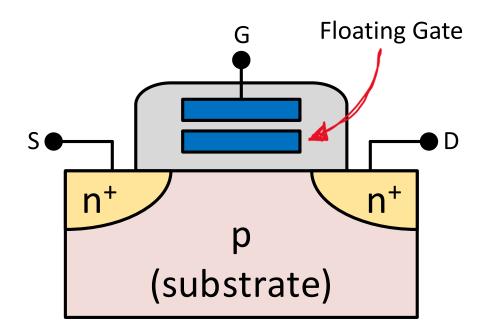
- Two different kinds of FGMOS
 - Changing the way electrons are injected into (programming) and removed from (erasing) floating gate
 - 1. FAMOS = Floating-gate Avalanche-injection MOS
 - 2. **FLOTOX** = **Flo**ating-gate **T**unnel-**Ox**ide MOS



FAMOS transistor

- Same layout and symbol as FGMOS
 - It was the first FGMOS





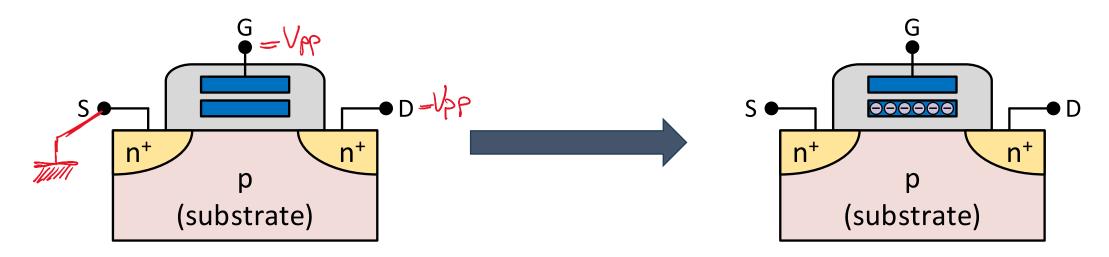


FAMOS transistor

- Working principle
 - Electrons injection (programming)
 - Avalanche effect = very high current → Floating-gate <u>Avalanche-injection</u> MOS

$$-V_G=V_D=V_{PP}$$
 (programming voltage, $V_{PP}\gg V_R$)

$$- V_S = 0$$





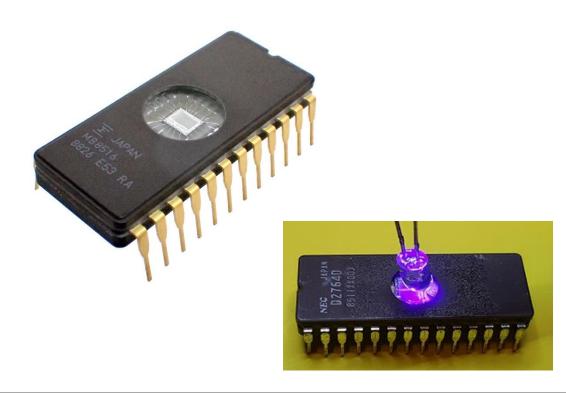
FAMOS transistor

- Working principle
 - Electrons removal (erasing)
 - Exposure to UV light



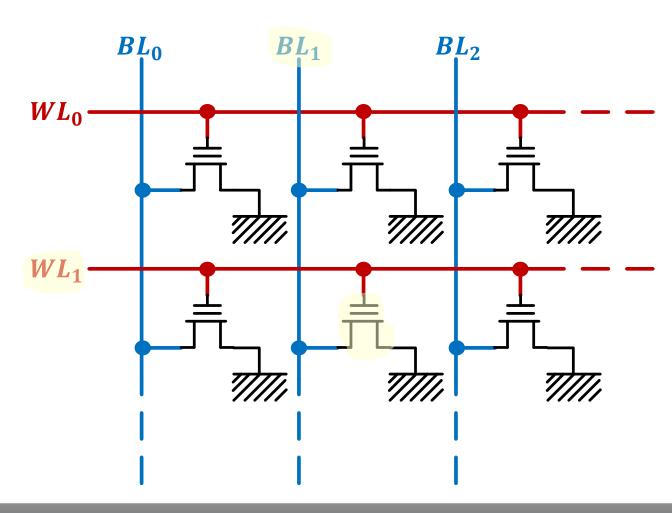


- It is based on FAMOS transistor
 - In practice, it is a PROM with FAMOS transistor instead of MOS + fuse (or anti-fuse)
 - Erasing procedure = exposure to <u>UV light</u>
 - From here the name → UV-EPROM
 - The chip is encapsulated in a <u>window</u>
 - Erasing the whole chip (ROM content) at once
 - Also called just EPROM
 - It was the first type of EPROM





- Working principle
 - Reading: the same as ROM/PROM
 - If transistor programmed → OFF
 - Otherwise (not programmed) → ON
 - Erasing: exposure to UV light
 - Programming Example
 - Programming cell (1,1)

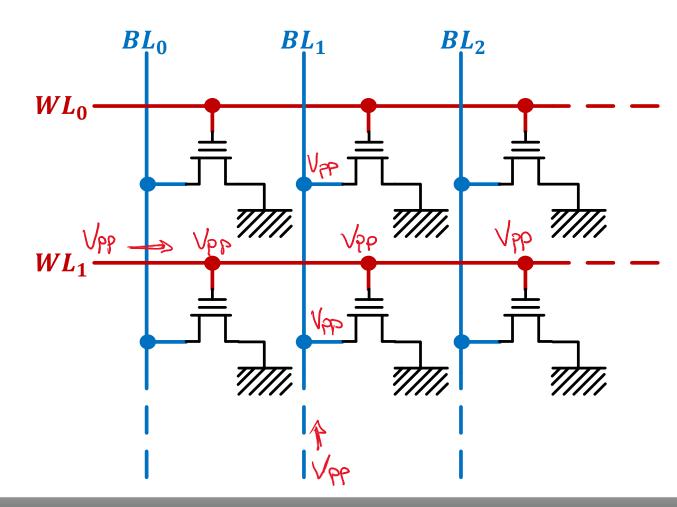




- Working principle
 - Reading: the same as ROM/PROM
 - If transistor programmed → OFF
 - Otherwise (not programmed) → ON
 - Erasing: exposure to UV light
 - Programming Example
 - Programming cell (1,1)

$$-V_G = WL_1 = V_{PP}$$

$$-V_D = BL_1 = V_{PP}$$



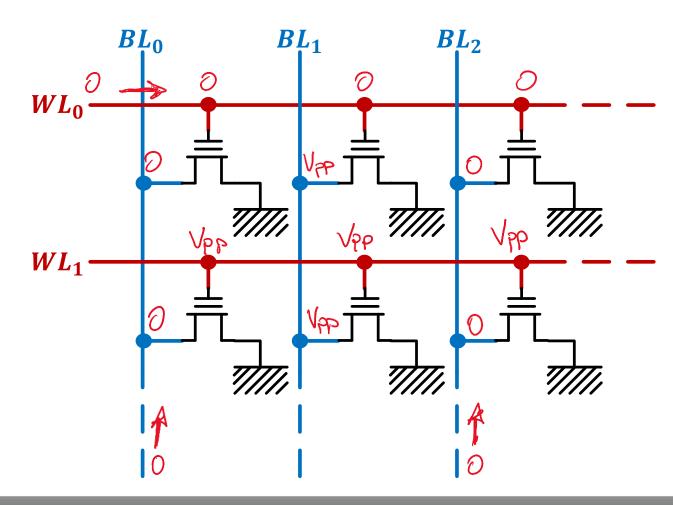


- Working principle
 - Reading: the same as ROM/PROM
 - If transistor programmed → OFF
 - Otherwise (not programmed) → ON
 - Erasing: exposure to UV light
 - Programming Example
 - Programming cell (1,1)

$$-V_G = WL_1 = V_{PP}$$

$$-V_D = BL_1 = V_{PP}$$

- All other $WL_i = 0$ and $BL_j = 0$!

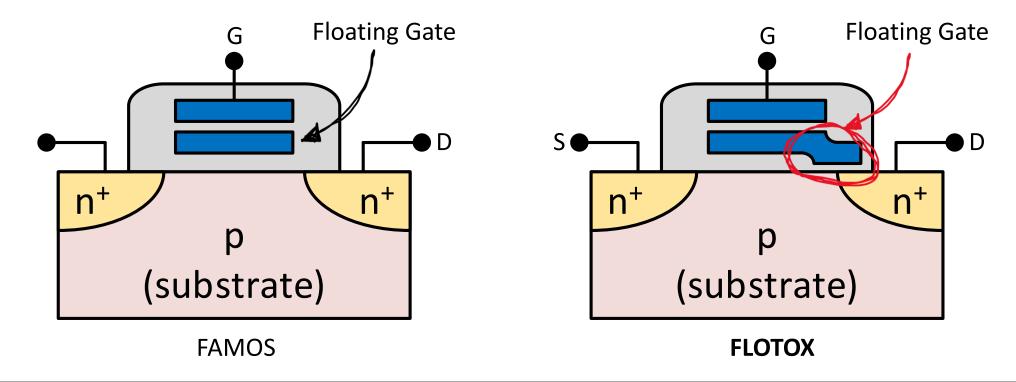




- Some differences w.r.t. FAMOS transistor
 - Floating gate extends over Drain and is separated from it by a very thin oxide layer

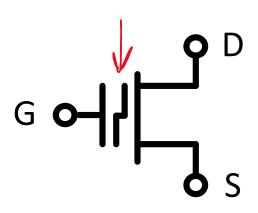


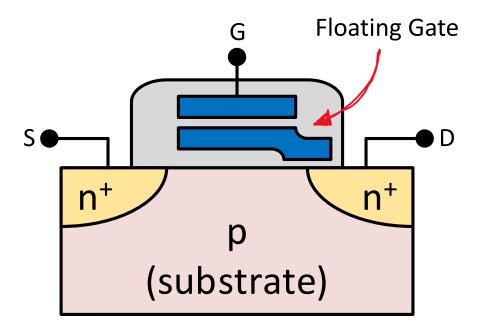
- Some differences w.r.t. FAMOS transistor
 - Floating gate extends over Drain and is separated from it by a very thin oxide layer





- Some differences w.r.t. FAMOS transistor
 - Also the symbol is different





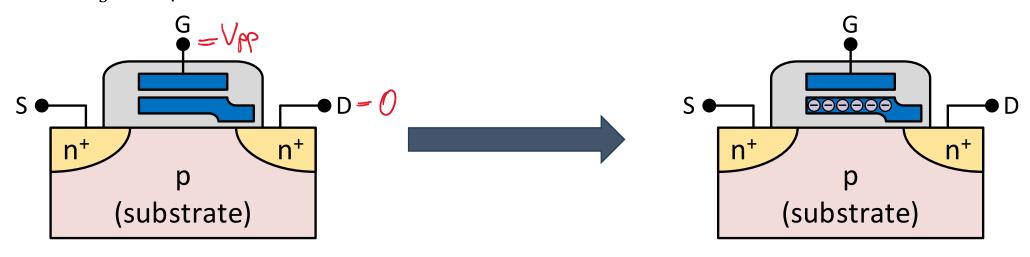


- Working principle
 - Electrons injection (programming)
 - Tunnel effect (thanks to the very thin oxide layer) → Floating-gate <u>Tunnel-Oxide</u> MOS

$$-V_G=V_{PP}$$

$$- V_D = 0$$

 $-V_S$: not specified



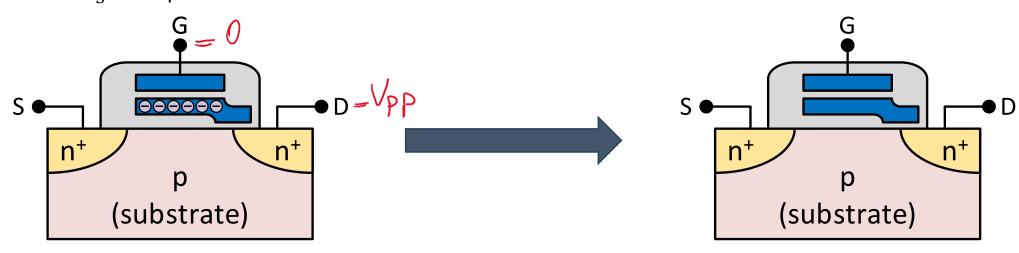


- Working principle
 - Electrons removal (erasing)
 - Tunnel effect (again)

$$-V_G=0$$

$$-V_D=V_{PP}$$

 $-V_S$: not specified



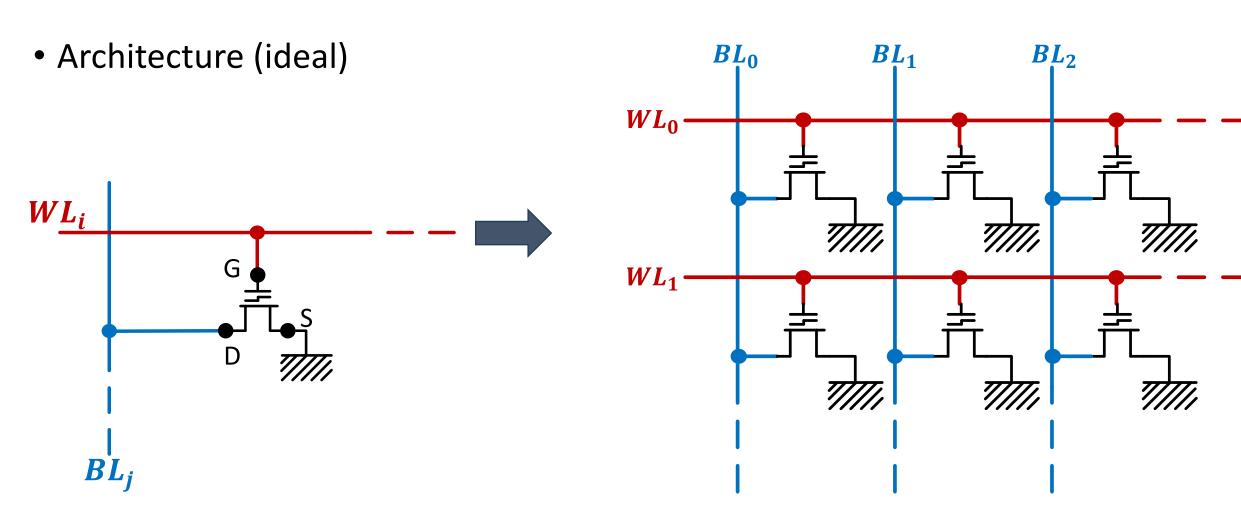
- It is based on FLOTOX transistor
 - In practice, it is a PROM with FLOTOX transistor instead of MOS + fuse (or anti-fuse)
 - Ideally !!!
 - Erasing procedure = tunnel effect due to <u>electrical</u> quantities
 - From here the name → EEPROM = Electrically Erasable PROM
 - Or E²PROM
 - Erasing only selected memory cells (FLOTOX transistors)

- It is based on FLOTOX transistor
 - In practice, it is a PROM with FLOTOX transistor instead of MOS + fuse (or anti-fuse)



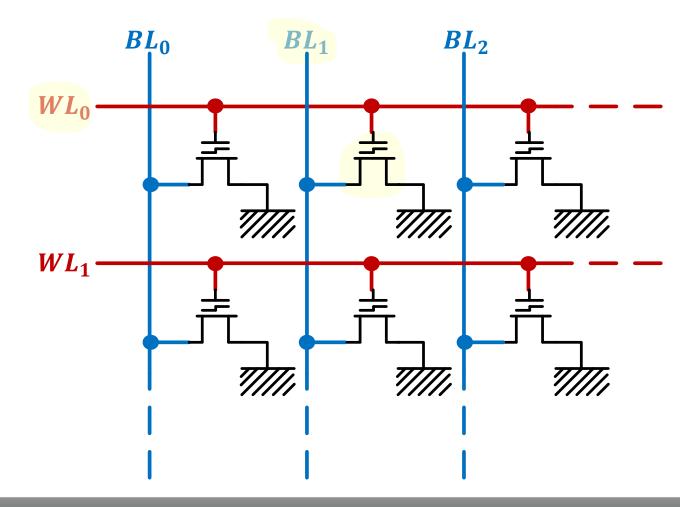
- Erasing procedure = tunnel effect due to <u>electrical</u> quantities
 - From here the name → EEPROM = Electrically Erasable PROM
 - Or E²PROM
 - Erasing only selected memory cells (FLOTOX transistors)







- Architecture (ideal)
 - Programming cell (0,1)

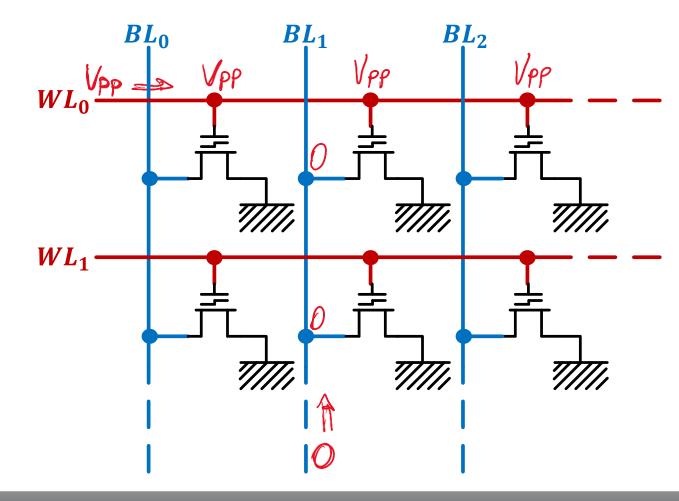




- Architecture (ideal)
 - Programming cell (0,1)

$$V_G = WL_0 = V_{PP}$$

$$V_D = BL_1 = 0$$



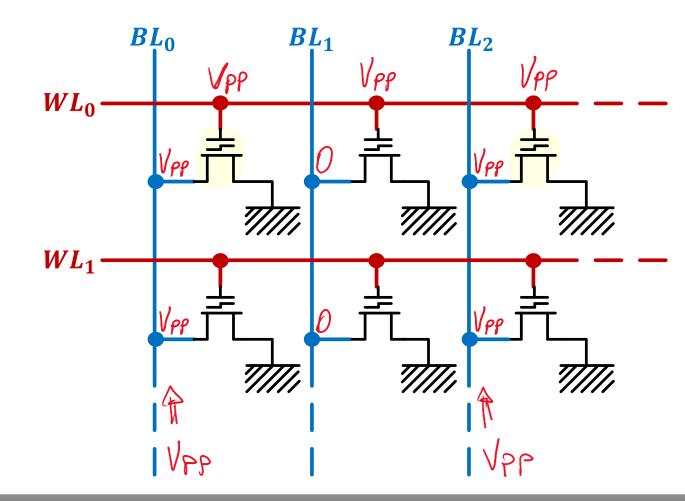


- Architecture (ideal)
 - Programming cell (0,1)

$$V_G = WL_0 = V_{PP}$$

•
$$V_D = BL_1 = 0$$

- All other $BL_j = V_{PP}$
 - Otherwise the other cells in the same WL₀ are programmed!



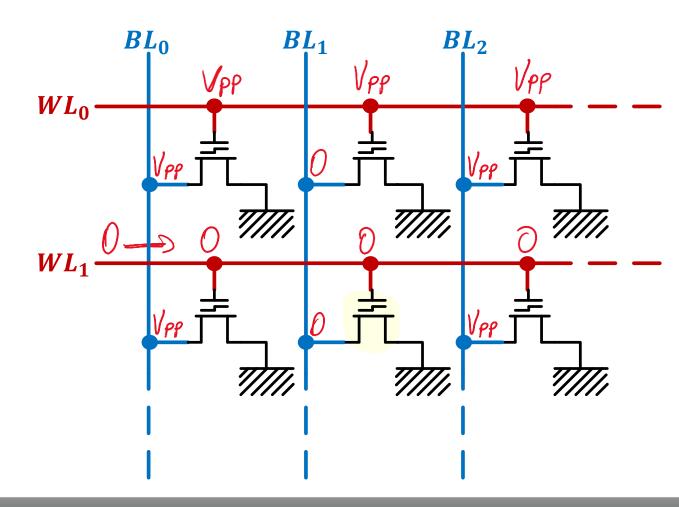


- Architecture (ideal)
 - Programming cell (0,1)

$$V_G = WL_0 = V_{PP}$$

•
$$V_D = BL_1 = 0$$

- All other $BL_j = V_{PP}$
 - Otherwise the other cells in the same WL_0 are programmed!
- All other $WL_i = 0$
 - Otherwise the other cells in the same BL₁ are programmed!



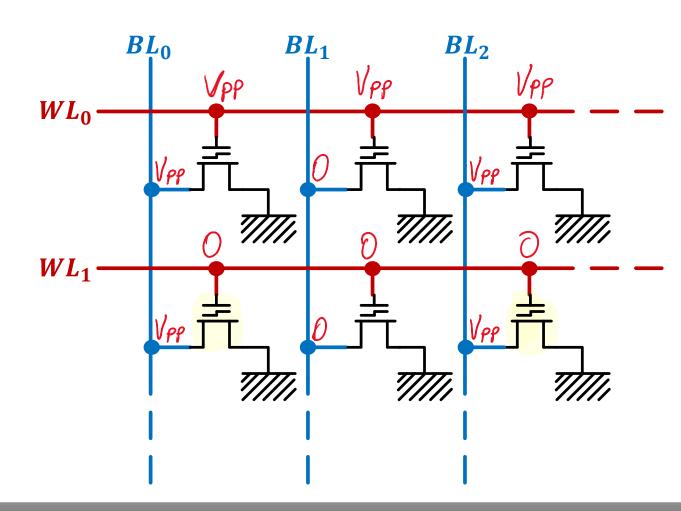


- Architecture (ideal)
 - Programming cell (0,1)

$$V_G = WL_0 = V_{PP}$$

•
$$V_D = BL_1 = 0$$

- All other $BL_j = V_{PP}$
 - Otherwise the other cells in the same WL_0 are programmed!
- All other $WL_i = 0$
 - Otherwise the other cells in the same BL_1 are programmed !
- But ... ERASE DISTURB !!!



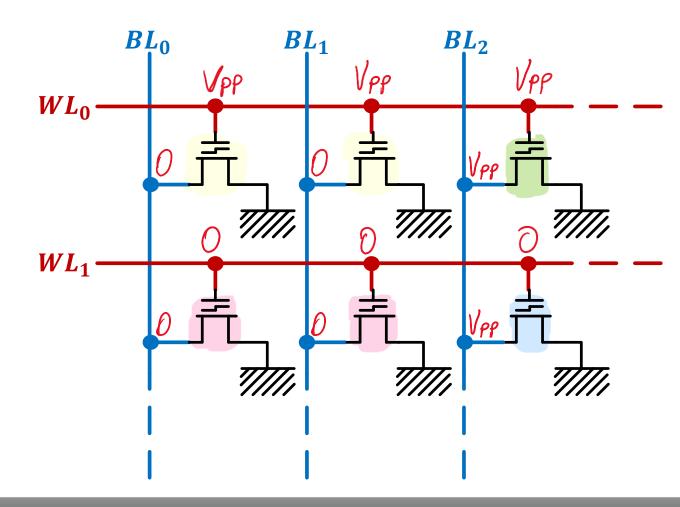


- Architecture (ideal)
 - Similarly, WRITE DISTURB !!!
 - Erasing cell (1,2)

•
$$V_G = WL_1 = 0$$

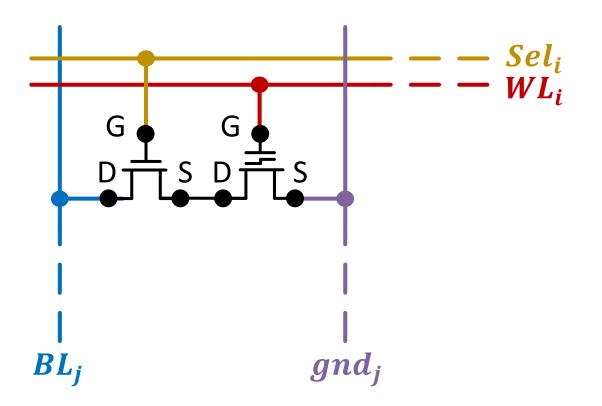
$$V_D = BL_2 = V_{PP}$$

- All other $BL_i = 0$
 - Otherwise the other cells in the same WL_1 are erased!
- All other $WL_i = V_{PP}$
 - Otherwise the other cells in the same BL_2 are erased!





- Architecture (real) To solve the problems
 - Memory cell
 - 2 transistors
 - 1x FLOTOX
 - 1x n-MOS (pass transistor)





- Architecture (real) To solve the problems
- Just for the sake of completeness
 - It won't be part of the exam!!

How should be driven

Operation	WL_i	Sel_i	BL_j	gnd_j	$WL_{i'}$	$Sel_{i'}$	$BL_{j'}$	$gnd_{j'}$
Program (WL_i , BL_j)	V_{CC}	V_{CC}	0	Z	0	0	V_{PP}	Z
Erase (WL_i , BL_j)	0	V_{CC}	V_{PP}	Z	V_{PP}	0	0	Z
Read (WL_i , BL_j)	V_{CC}	V_{CC}	Q	0	0	0		0

- Notes
 - $WL_{i'}$, $Sel_{i'}$, $BL_{j'}$, and $gnd_{j'}$ indicate, respectively, all other WL, Sel, BL, and gnd different from WL_i , Sel_i , BL_j , and gnd_j
 - -Z = high impedance



Thank you for your attention

Luca Crocetti (luca.crocetti@unipi.it)